

6. A structure comprising:
- a semiconductor device having bumps;
 - a board having pads so that each of the bumps is joined to a corresponding one of the pads,
 - each of the pads having a deformed portion with which a corresponding one of the bumps contact;
 - and
 - an insulating adhesive provided between the semiconductor device and the board, wherein contraction of the insulating adhesive maintains joints of the bumps and the pads, said joints